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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR: Todd H. Buley)
SERIAL NO.: 10/605,257)
FILING DATE: September 18, 2003) DATE: October 11, 2005
FOR: INCLINED SOLDER WAVE METHODOLOGY FOR WAVE
SOLDERING DOUBLE SIDED PIN-IN-HOLE ELECTRONIC
COMPONENTS

CHANGE OF CORRESPONDENCE ADDRESS FOR ALL PURPOSES

**Mail Stop ISSUE FEE
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P.O. Box 1450
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Dear Sir:

Pursuant to 37 CFR §1.33, please change the correspondence address, (Customer No. 32074), for all purposes for the above identified patent application and resulting patent to:

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Respectfully submitted,



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